ABSTRACT OF THE DISCLOSURE

EXTENDED LEAD PACKAGE

This invention provides an extended lead package and method of forming the extended lead package for electronic circuit packages. A lead frame having extended leads is used. The extended leads extend under the bottom side of an integrated circuit element or chip. The bottom side of the chip is attached to the extended leads using bonding material which is a thermal conductor and an electrical insulator. Electrical connections between the chip input/output pads and the leads are provided by wire bonds using standard wire bonding techniques. The bonding material can be a tape having adhesive on one or both sides which attaches the chip to the lead frame using mechanical pressure, and/or other means such as curing or the addition of heat. Thermal energy is removed from the package by the thermal conduction path provided by the bonding material. The completed assembly can be encapsulated using standard methods.

(FIGURE 4 IS SUGGESTED FOR PUBLICATION)